100-Lead Plastic Thin Quad Flat Pack (4SB) - 14x14x1.0 mm Body [TQFP] With 6.3 mm Grooved Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		MILLIMETERS		
Dimensio	n Limits	MIN	NOM	MAX	
Number of Terminals	Ν	100			
Pitch	е	0.50 BSC			
Overall Height	Α	-	-	1.20	
Standoff	A1	0.05	-	0.15	
Molded Package Thickness	A2	0.95	1.00	1.05	
Overall Length	D	16.00 BSC			
Overall Length	D1	14.00 BSC			
Exposed Pad Length	D2	6.20	6.30	6.40	
Overall Width	E	16.00 BSC			
Overall Width	E1	14.00 BSC			
Exposed Pad Width	E2	6.20	6.30	6.40	
Terminal Width	b	0.17	0.20	0.27	
Terminal Thickness	С	0.09	0.13	0.20	
Terminal Length	L	0.45	0.60	0.75	
Footprint	L1	1.00 REF			
Lead Bend Radius	R1	0.08	-	-	
Lead Bend Radius	R2	0.08	-	0.20	
Foot Angle	θ	0°	3.5°	7°	
Lead Angle	θ1	0°	-	-	
Mold Draft Angle	θ2	11°	12°	13°	
Mold Draft Angle	θ3	11°	12°	13°	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.